

DESCRIPTION

The SM520BF~SM5200BF are available in SMBF package.

FEATURES

- Metal silicon junction, majority carrier conduction
- For surface mounted applications
- Low power loss, high efficiency
- High forward surge current capability
- For use in low voltage, high frequency inverters, free wheeling, and polarity protection applications
- Available in SMBF package

ORDERING INFORMATION

Package Type	Part Number				
SMBF	SM520BF				
	SM540BF				
	SM560BF				
	SM580BF				
	SM5100BF				
	SM5120BF				
	SM5150BF				
	SM5200BF				
Note	5,000pcs/Reel				
AiT provides all RoHS Compliant Products					

MECHANICAL DATA

Case: SMBF

Terminals: Solderable per MIL-STD-750,

Method 2026

Approx. Weight: 57mg / 0.002oz

PIN DESCRIPTION





ABSOLUTE MAXIMUM RATINGS

Ratings at 25°C ambient temperature unless otherwise specified. Single phase, half wave, 60Hz resistive or inductive load, for capacitive load, derate by 20 %

Parameter		Symbol	SM 520BF	SM 540BF	SM 560BF	SM 580BF	SM 5100BF	SM 5120BF	SM 5150BF	SM 5200BF	Unit
Maximum Repetitive Pea Reverse Voltage	Vrrm	20	40	60	80	100	120	150	200	V	
Maximum RMS Voltage	V _{RMS}	14	28	42	56	70	84	105	140	V	
Maximum DC Blocking	V _{DC}	20	40	60	80	100	120	150	200	V	
Maximum Average Forward Rectified Current		IF(AV)	5.0							A	
Peak Forward Surge Cu 8.3ms Single Half Sine-v Superimposed on Rated (JEDEC Method)	I _{FSM}	150							A		
Max Instantaneous Forw Voltage at 5A	VF	0.45 0.55 0.70 0.85					V				
Maximum DC Reverse Current At Rated DC Reverse Voltage	T _A =25°C T _A =100°C	IR	1.0 50						mA		
Typical Junction Capacitance ^{NOTE1}		Cj	800 500					pF			
Typical Thermal Resistance NOTE2		Reja	40							°C/W	
Operating Junction Temperature Range		TJ	-55 ~ +125							°C	
Storage Temperature Range		Tstg	-55 ~ +150							°C	

NOTE1: Measured at 1MHz and applied reverse voltage of 4 V D.C.

NOTE2: P.C.B. mounted with 0.5 X 0.5" (12.7 X 12.7 mm) copper pad areas.



TYPICAL PERFORMANCE CHARACTERISTICS

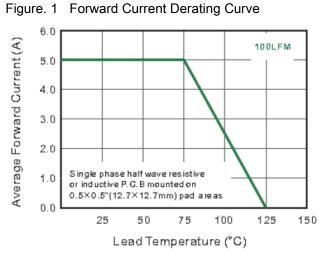


Figure. 3 Typical Forward Characteristic

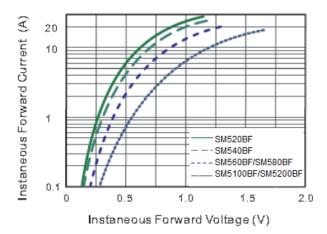


Figure. 5 Maximum Non-repetitive Peak Forward Surge Current

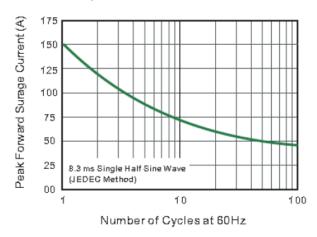


Figure. 2 Typical Reverse Characteristics

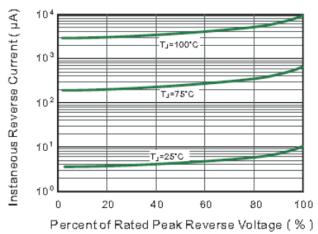


Figure. 4 Typical Junction Capacitance

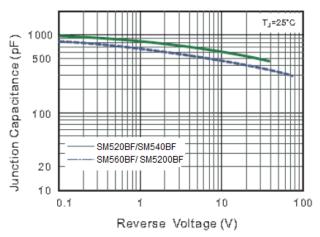
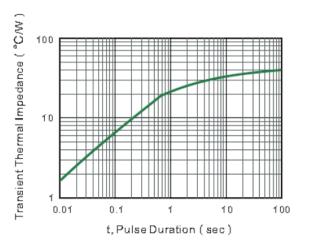


Figure. 6 Typical Transient Thermal Impedance

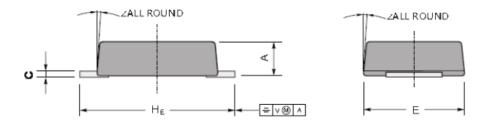


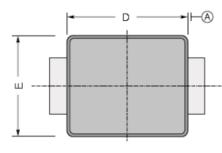


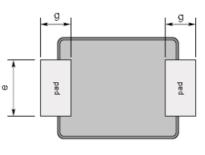
PACKAGE INFORMATION

Dimension in SMBF Package (Unit: mm)

Plastic surface mounted package; 2 leads



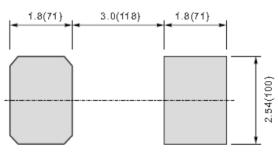




Top View

Bottom View

The recommended mounting pad size



Unit: mm(mil)

UN	UNIT		С	D	Е	HE	е	g	2
1	Max	1.3	0.26	4.4	3.7	5.5	2.2	1.0	
mm	Min	1.1	0.18	4.2	3.5	5.1	1.9	1.0	^ °
mil	Max	51	10	173	146	216	86	40	9°
	Min	43	7	165	138	200	75	40	



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